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Intel - 5SGXEA7K3F35I3LN Datasheet



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Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Details	
Product Status	Obsolete
Number of LABs/CLBs	234720
Number of Logic Elements/Cells	622000
Total RAM Bits	51200000
Number of I/O	432
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxea7k3f35i3ln

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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Transceiver Speed				Core Spe	ed Grade			
Grade	C1	C2, C2L	C3	C4	12, 12L	13, 13L	I 3YY	14
3		Yes	Yes	Yes		Yes	Yes (4)	Yes
GX channel—8.5 Gbps		165	165	165		163	163 17	165

Table 1. Stratix V GX and GS Commercial and Industrial Speed Grade Offering ^{(1), (2), (3)} (Part 2 of 2)

Notes to Table 1:

(1) C = Commercial temperature grade; I = Industrial temperature grade.

(2) Lower number refers to faster speed grade.

(3) C2L, I2L, and I3L speed grades are for low-power devices.

(4) I3YY speed grades can achieve up to 10.3125 Gbps.

Table 2 lists the industrial and commercial speed grades for the Stratix V GT devices. **Table 2. Stratix V GT Commercial and Industrial Speed Grade Offering** ⁽¹⁾, ⁽²⁾

Transaction Oracle Oracle	Core Speed Grade					
Transceiver Speed Grade	C1	C2	12	13		
2 GX channel—12.5 Gbps GT channel—28.05 Gbps	Yes	Yes	_	_		
3 GX channel—12.5 Gbps GT channel—25.78 Gbps	Yes	Yes	Yes	Yes		

Notes to Table 2:

(1) C = Commercial temperature grade; I = Industrial temperature grade.

(2) Lower number refers to faster speed grade.

Absolute Maximum Ratings

Absolute maximum ratings define the maximum operating conditions for Stratix V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.



Conditions other than those listed in Table 3 may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 3.	Absolute	Maximum	Ratings	for Stratix \	/ Devices	(Part 1 of 2)
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Symbol	Description	Minimum	Maximum	Unit
V _{CC}	Power supply for core voltage and periphery circuitry	-0.5	1.35	V
V _{CCPT}	Power supply for programmable power technology	-0.5	1.8	V
V _{CCPGM}	Power supply for configuration pins	-0.5	3.9	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	-0.5	3.4	V
V _{CCBAT}	Battery back-up power supply for design security volatile key register	-0.5	3.9	V
V _{CCPD}	I/O pre-driver power supply	-0.5	3.9	V
V _{CCIO}	I/O power supply	-0.5	3.9	V

Table 5 lists the maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage of device lifetime. The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% of the duty cycle. For example, a signal that overshoots to 3.95 V can be at 3.95 V for only ~21% over the lifetime of the device; for a device lifetime of 10 years, the overshoot duration amounts to ~2 years.

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Symbol	Description	Condition (V)	Overshoot Duration as % @ T _J = 100°C	Unit
		3.8	100	%
		3.85	64	%
		3.9	36	%
	AC input voltage	3.95	21	%
Vi (AC)		4	12	%
		4.05	7	%
		4.1	4	%
		4.15	2	%
		4.2	1	%

Table 5. Maximum Allowed Overshoot During Transitions

Figure 1. Stratix V Device Overshoot Duration



This section lists the functional operating limits for the AC and DC parameters for Stratix V devices. Table 6 lists the steady-state voltage and current values expected from Stratix V devices. Power supply ramps must all be strictly monotonic, without plateaus.

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 1 of 2)

Symbol	Description	Condition	Min ⁽⁴⁾	Тур	Max ⁽⁴⁾	Unit
	Core voltage and periphery circuitry power supply (C1, C2, I2, and I3YY speed grades)	_	0.87	0.9	0.93	V
V _{CC}	Core voltage and periphery circuitry power supply (C2L, C3, C4, I2L, I3, I3L, and I4 speed grades) ⁽³⁾	_	0.82	0.85	0.88	V
V _{CCPT}	Power supply for programmable power technology	_	1.45	1.50	1.55	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	_	2.375	2.5	2.625	V
VI (1)	I/O pre-driver (3.0 V) power supply	_	2.85	3.0	3.15	V
V _{CCPD} ⁽¹⁾	I/O pre-driver (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (3.0 V) power supply		2.85	3.0	3.15	V
	I/O buffers (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply		1.71	1.8	1.89	V
V _{CCIO}	I/O buffers (1.5 V) power supply	_	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply	_	1.283	1.35	1.45	V
	I/O buffers (1.25 V) power supply	_	1.19	1.25	1.31	V
	I/O buffers (1.2 V) power supply	_	1.14	1.2	1.26	V
	Configuration pins (3.0 V) power supply	_	2.85	3.0	3.15	V
V _{CCPGM}	Configuration pins (2.5 V) power supply	_	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	_	1.71	1.8	1.89	V
V _{CCA_FPLL}	PLL analog voltage regulator power supply	_	2.375	2.5	2.625	V
V _{CCD_FPLL}	PLL digital voltage regulator power supply	_	1.45	1.5	1.55	V
V _{CCBAT} (2)	Battery back-up power supply (For design security volatile key register)	_	1.2	_	3.0	V
VI	DC input voltage	_	-0.5	_	3.6	V
V ₀	Output voltage	—	0	—	V _{CCIO}	V
т	Operating junction temperature	Commercial	0	—	85	°C
TJ	Operating junction temperature	Industrial	-40	_	100	°C

Symbol	Description	Devices	Minimum ⁽⁴⁾	Typical	Maximum ⁽⁴⁾	Unit
			0.82	0.85	0.88	
V _{CCR_GXBR}	Receiver analog power supply (right side)	GX, GS, GT	0.87	0.90	0.93	v
(2)	Receiver analog power supply (right side)	un, us, ui	0.97	1.0	1.03	v
			1.03	1.05	1.07	
V _{CCR_GTBR}	Receiver analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
			0.82	0.85	0.88	
V _{CCT_GXBL}	Transmitter analog power supply (left side)	GX, GS, GT	0.87	0.90	0.93	V
			0.97	1.0	1.03	
			1.03	1.05	1.07	
		GX, GS, GT	0.82	0.85	0.88	V
V _{CCT_GXBR}	Transmitter analog power supply (right side)		0.87	0.90	0.93	
(2)			0.97	1.0	1.03	
			1.03	1.05	1.07	
V _{CCT_GTBR}	Transmitter analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
V_{CCL_GTBR}	Transmitter clock network power supply	GT	1.02	1.05	1.08	V
V _{CCH_GXBL}	Transmitter output buffer power supply (left side)	GX, GS, GT	1.425	1.5	1.575	V
V _{CCH_GXBR}	Transmitter output buffer power supply (right side)	GX, GS, GT	1.425	1.5	1.575	V

Table 7.	Recommended Transceiver Power Supply Operating Conditions for Stratix V GX,	GS, and GT Devices
(Part 2	of 2)	

Notes to Table 7:

(1) This supply must be connected to 3.0 V if the CMU PLL, receiver CDR, or both, are configured at a base data rate > 6.5 Gbps. Up to 6.5 Gbps, you can connect this supply to either 3.0 V or 2.5 V.

(2) Refer to Table 8 to select the correct power supply level for your design.

(3) When using ATX PLLs, the supply must be 3.0 V.

(4) This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

	Description		Calibration Accuracy				
Symbol		Conditions	C1	C2,12	C3,I3, I3YY	C4,14	Unit
50-Ω R _S	Internal series termination with calibration (50- Ω setting)	V _{CCI0} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%
34-Ω and 40-Ω R _S	Internal series termination with calibration (34- Ω and 40- Ω setting)	V _{CCI0} = 1.5, 1.35, 1.25, 1.2 V	±15	±15	±15	±15	%
48-Ω, 60-Ω, 80-Ω, and 240-Ω R _S	Internal series termination with calibration (48- Ω , 60- Ω , 80- Ω , and 240- Ω setting)	V _{CCI0} = 1.2 V	±15	±15	±15	±15	%
50-Ω R _T	Internal parallel termination with calibration (50-Ω setting)	V _{CCIO} = 2.5, 1.8, 1.5, 1.2 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
20- $Ω$, 30- $Ω$, 40- $Ω$,60- $Ω$, and 120- $Ω$ R _T	Internal parallel termination with calibration ($20 \cdot \Omega$, $30 \cdot \Omega$, $40 \cdot \Omega$, $60 \cdot \Omega$, and $120 \cdot \Omega$ setting)	V _{CCI0} = 1.5, 1.35, 1.25 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
60-Ω and 120-Ω R_T	Internal parallel termination with calibration (60- Ω and 120- Ω setting)	V _{CCI0} = 1.2	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
$\begin{array}{l} \textbf{25-}\Omega\\ \textbf{R}_{S_left_shift} \end{array}$	Internal left shift series termination with calibration (25- Ω R _{S_left_shift} setting)	V _{CCI0} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%

Table 11. OCT Calibration Accurat	y Specifications for Stratix V Devices ⁽¹⁾ ((Part 2 of 2)
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Note to Table 11:

(1) OCT calibration accuracy is valid at the time of calibration only.

Table 12 lists the Stratix V OCT without calibration resistance to PVT changes.

			Resistance Tolerance					
Symbol	Description	Conditions	C1	C2,I2	C3, I3, I3YY	C4, I4	Unit	
25-Ω R, 50-Ω R _S	Internal series termination without calibration (25- Ω setting)	$V_{CCIO} = 3.0$ and 2.5 V	±30	±30	±40	±40	%	
25-Ω R _S	Internal series termination without calibration (25-Ω setting)	$V_{CCI0} = 1.8$ and 1.5 V	±30	±30	±40	±40	%	
25-Ω R _S	Internal series termination without calibration (25-Ω setting)	V _{CCI0} = 1.2 V	±35	±35	±50	±50	%	

Symbol	Description	V _{CCIO} (V)	Typical	Unit
		3.0	0.189	
	OCT variation with temperature without recalibration	2.5	0.208	
dR/dT		1.8	0.266	%/°C
	without robalibration	1.5	0.273	
		1.2	0.317	

Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 2 of 2)⁽¹⁾

Note to Table 13:

(1) Valid for a V_{CCIO} range of $\pm 5\%$ and a temperature range of 0° to 85°C.

Pin Capacitance

Table 14 lists the Stratix V device family pin capacitance.

Table 14. Pin Capacitance for Stratix V Devices

Symbol	Value	Unit	
C _{IOTB}	Input capacitance on the top and bottom I/O pins	6	pF
C _{IOLR}	Input capacitance on the left and right I/O pins	6	рF
C _{OUTFB}	Input capacitance on dual-purpose clock output and feedback pins	6	рF

Hot Socketing

Table 15 lists the hot socketing specifications for Stratix V devices.

Table 15.	Hot Socketing Specifications for Stratix V Devices
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Symbol	Description	Maximum
I _{IOPIN (DC)}	DC current per I/O pin	300 μA
I _{IOPIN (AC)}	AC current per I/O pin	8 mA ⁽¹⁾
I _{XCVR-TX (DC)}	DC current per transceiver transmitter pin	100 mA
I _{XCVR-RX (DC)}	DC current per transceiver receiver pin	50 mA

Note to Table 15:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, $|I_{10PIN}| = C dv/dt$, in which C is the I/O pin capacitance and dv/dt is the slew rate.

- You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.
- ***** For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

Symbol/	Conditions	Trai	nsceive Grade	r Speed 1	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Reconfiguration clock (mgmt_clk_clk) frequency	_	100	_	125	100		125	100		125	MHz
Receiver											
Supported I/O Standards	_			1.4-V PCM	L, 1.5-V	PCML,	2.5-V PCM	L, LVPE	CL, and	d LVDS	
Data rate (Standard PCS) (9), (23)	_	600	_	12200	600	_	12200	600	_	8500/ 10312.5 (24)	Mbps
Data rate (10G PCS) ^{(9),} ⁽²³⁾		600	_	14100	600	_	12500	600	_	8500/ 10312.5 (24)	Mbps
Absolute V_{MAX} for a receiver pin (5)		_	_	1.2	—	_	1.2	—	_	1.2	V
Absolute V _{MIN} for a receiver pin	_	-0.4	_		-0.4	_	_	-0.4	_	_	V
Maximum peak- to-peak differential input voltage V _{ID} (diff p- p) before device configuration ⁽²²⁾	_	_	_	1.6	_	_	1.6	_	_	1.6	V
Maximum peak- to-peak	V _{CCR_GXB} = 1.0 V/1.05 V (V _{ICM} = 0.70 V)	_	_	2.0	_	_	2.0	_	_	2.0	V
differential input voltage V_{ID} (diff p- p) after device configuration ⁽¹⁸⁾ ,	$V_{CCR_GXB} = 0.90 V$ (V _{ICM} = 0.6 V)	_	_	2.4	_	_	2.4	_	_	2.4	V
(22)	$V_{CCR_GXB} = 0.85 V$ (V _{ICM} = 0.6 V)			2.4			2.4			2.4	V
Minimum differential eye opening at receiver serial input pins ^{(6), (22),} (27)	_	85		_	85		_	85	_	_	mV

Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 3 of 7)

Symbol/ Description	Conditions	Tra	nsceive Grade	r Speed 1	Tra	nsceive Grade	r Speed 2	Trai	nsceive Grade	r Speed 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	85– Ω setting		85 ± 30%		—	85 ± 30%			85 ± 30%		Ω
Differential on-	100–Ω setting	_	100 ± 30%		_	100 ± 30%		_	100 ± 30%		Ω
chip termination resistors ⁽²¹⁾	rmination	_	120 ± 30%		_	120 ± 30%		_	120 ± 30%		Ω
		_	150 ± 30%	_	_	150 ± 30%		_	150 ± 30%		Ω
	V _{CCR_GXB} = 0.85 V or 0.9 V full bandwidth		600		_	600	_		600		mV
V _{ICM} (AC and DC coupled)	V _{CCR_GXB} = 0.85 V or 0.9 V half bandwidth	_	600	_	_	600	_	_	600	_	mV
coupleu)	V _{CCR_GXB} = 1.0 V/1.05 V full bandwidth	_	700		_	700			700		mV
	V _{CCR_GXB} = 1.0 V half bandwidth		750	_	_	750	_	_	750	_	mV
t _{LTR} ⁽¹¹⁾	_	—	—	10	_	—	10	—	—	10	μs
t _{LTD} (12)	_	4			4			4			μs
t _{LTD_manual} ⁽¹³⁾		4			4			4	_		μs
t _{LTR_LTD_manual} ⁽¹⁴⁾		15			15	—		15	—		μs
Run Length	_	_		200		—	200		—	200	UI
Programmable equalization (AC Gain) ⁽¹⁰⁾	Full bandwidth (6.25 GHz) Half bandwidth (3.125 GHz)			16	_		16	_		16	dB

 Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 4 of 7)

Symbol/	Conditions	:	Transceive Speed Grade			Transceive peed Grade		Unit				
Description		Min	Тур	Max	Min	Тур	Max					
Reference Clock												
Supported I/O Standards	Dedicated reference clock pin	1.2-V PCN	/IL, 1.4-V PC	ML, 1.5-V P	CML, 2.5-V and HCSL	PCML, Diffe	rential LVPE	ECL, LVDS				
	RX reference clock pin	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS										
Input Reference Clock Frequency (CMU PLL) ⁽⁶⁾	_	40	_	710	40	_	710	MHz				
Input Reference Clock Frequency (ATX PLL) ⁽⁶⁾	_	100	-	710	100	_	710	MHz				
Rise time	20% to 80%		_	400		—	400					
Fall time	80% to 20%			400	—		400	ps				
Duty cycle	—	45		55	45		55	%				
Spread-spectrum modulating clock frequency	PCI Express (PCIe)	30	_	33	30	_	33	kHz				
Spread-spectrum downspread	PCle	_	0 to -0.5		_	0 to -0.5	_	%				
On-chip termination resistors ⁽¹⁹⁾	_	_	100	_	_	100	_	Ω				
Absolute V _{MAX} ⁽³⁾	Dedicated reference clock pin		_	1.6	_	_	1.6	V				
	RX reference clock pin	_	_	1.2	_	_	1.2					
Absolute V _{MIN}	—	-0.4	—	—	-0.4	—	—	V				
Peak-to-peak differential input voltage	_	200	_	1600	200	_	1600	mV				
V _{ICM} (AC coupled)	Dedicated reference clock pin		1050/1000 (2)		1050/1000 (2)	mV				
	RX reference clock pin	1	.0/0.9/0.85 (22)	1.	V						
V _{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	mV				

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 1 of 5) ⁽¹⁾

Symbol/	Conditions	5	Transceiver Speed Grade			Transceive peed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	
Differential on-chip termination resistors ⁽⁷⁾	GT channels		100	_	_	100	_	Ω
	85- Ω setting	_	85 ± 30%	_	_	85 ± 30%	_	Ω
Differential on-chip termination resistors	100-Ω setting	_	100 ± 30%	_	_	100 ± 30%	_	Ω
for GX channels ⁽¹⁹⁾	120-Ω setting	_	120 ± 30%	_	_	120 ± 30%	_	Ω
	150-Ω setting		150 ± 30%	_	_	150 ± 30%	_	Ω
V _{ICM} (AC coupled)	GT channels		650		—	650	—	mV
	VCCR_GXB = 0.85 V or 0.9 V		600	_	_	600		mV
VICM (AC and DC coupled) for GX Channels	VCCR_GXB = 1.0 V full bandwidth		700	_	_	700	_	mV
	VCCR_GXB = 1.0 V half bandwidth		750	_	_	750	_	mV
t _{LTR} ⁽⁹⁾	—	—	—	10	—	—	10	μs
t _{LTD} ⁽¹⁰⁾		4			4			μs
t _{LTD_manual} ⁽¹¹⁾	—	4	—	—	4	—	_	μs
t _{LTR_LTD_manual} ⁽¹²⁾	_	15			15	—		μs
Run Length	GT channels	_	_	72	—	—	72	CID
nun Lengin	GX channels				(8)			
CDR PPM	GT channels			1000	_	—	1000	± PPM
	GX channels				(8)			
Programmable	GT channels	_	_	14	—	—	14	dB
equalization (AC Gain) ⁽⁵⁾	GX channels				(8)			
Programmable	GT channels	_	—	7.5	—	—	7.5	dB
DC gain ⁽⁶⁾	GX channels				(8)			
Differential on-chip termination resistors ⁽⁷⁾	GT channels	_	100	_	_	100	_	Ω
Transmitter	·1							
Supported I/O Standards	_	1.4-V and 1.5-V PCML						
Data rate (Standard PCS)	GX channels	600	_	8500	600	_	8500	Mbps
Data rate (10G PCS)	GX channels	600		12,500	600	_	12,500	Mbps

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 3 of 5)⁽¹⁾

Figure 6 shows the Stratix V DC gain curves for GT channels.

Figure 6. DC Gain Curves for GT Channels

Transceiver Characterization

This section summarizes the Stratix V transceiver characterization results for compliance with the following protocols:

- Interlaken
- 40G (XLAUI)/100G (CAUI)
- 10GBase-KR
- QSGMII
- XAUI
- SFI
- Gigabit Ethernet (Gbe / GIGE)
- SPAUI
- Serial Rapid IO (SRIO)
- CPRI
- OBSAI
- Hyper Transport (HT)
- SATA
- SAS
- CEI

PLL Specifications

Table 31 lists the Stratix V PLL specifications when operating in both the commercial junction temperature range (0° to 85° C) and the industrial junction temperature range (-40° to 100° C).

Table 31. PLL Specifications for Stratix V Devices (Part 1 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
	Input clock frequency (C1, C2, C2L, I2, and I2L speed grades)	5	_	800 (1)	MHz
f _{IN}	Input clock frequency (C3, I3, I3L, and I3YY speed grades)	5	_	800 (1)	MHz
	Input clock frequency (C4, I4 speed grades)	5	_	650 ⁽¹⁾	MHz
f _{INPFD}	Input frequency to the PFD	5	—	325	MHz
f _{finpfd}	Fractional Input clock frequency to the PFD	50	_	160	MHz
	PLL VCO operating range (C1, C2, C2L, I2, I2L speed grades)	600	_	1600	MHz
f _{VCO}	PLL VCO operating range (C3, I3, I3L, I3YY speed grades)	600	_	1600	MHz
	PLL VCO operating range (C4, I4 speed grades)	600	—	1300	MHz
t _{einduty}	Input clock or external feedback clock input duty cycle	40		60	%
	Output frequency for an internal global or regional clock (C1, C2, C2L, I2, I2L speed grades)	—	_	717 ⁽²⁾	MHz
f _{ouт}	Output frequency for an internal global or regional clock (C3, I3, I3L speed grades)	_	_	650 ⁽²⁾	MHz
	Output frequency for an internal global or regional clock (C4, I4 speed grades)	_	_	580 ⁽²⁾	MHz
	Output frequency for an external clock output (C1, C2, C2L, I2, I2L speed grades)	_	_	800 (2)	MHz
f _{out_ext}	Output frequency for an external clock output (C3, I3, I3L speed grades)	_	_	667 ⁽²⁾	MHz
	Output frequency for an external clock output (C4, I4 speed grades)	_	_	553 ⁽²⁾	MHz
t _{outduty}	Duty cycle for a dedicated external clock output (when set to 50%)	45	50	55	%
t _{FCOMP}	External feedback clock compensation time	_	—	10	ns
f _{dyconfigclk}	Dynamic Configuration Clock used for <code>mgmt_clk</code> and <code>scanclk</code>	_	_	100	MHz
t _{LOCK}	Time required to lock from the end-of-device configuration or deassertion of areset	_	_	1	ms
t _{olock}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	_	_	1	ms
	PLL closed-loop low bandwidth		0.3	—	MHz
f _{CLBW}	PLL closed-loop medium bandwidth	_	1.5		MHz
	PLL closed-loop high bandwidth (7)		4	—	MHz
t _{PLL_PSERR}	Accuracy of PLL phase shift			±50	ps
t _{areset}	Minimum pulse width on the areset signal	10	_		ns

		Resour	ces Used			Pe	erforman	ce			
Memory	Mode	ALUTS	Memory	C1	C2, C2L	C3	C4	12, 12L	13, 13L, 13YY	14	Unit
	Single-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port with the read-during-write option set to Old Data , all supported widths	0	1	525	525	455	400	525	455	400	MHz
M20K Block	Simple dual-port with ECC enabled, 512 × 32	0	1	450	450	400	350	450	400	350	MHz
	Simple dual-port with ECC and optional pipeline registers enabled, 512 × 32	0	1	600	600	500	450	600	500	450	MHz
	True dual port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	ROM, all supported widths	0	1	700	700	650	550	700	500	450	MHz

Table 33. Memory Block Performance Specifications for Stratix V Devices ^{(1), (2)} (Part 2 of 2)

Notes to Table 33:

(1) To achieve the maximum memory block performance, use a memory block clock that comes through global clock routing from an on-chip PLL set to **50**% output duty cycle. Use the Quartus II software to report timing for this and other memory block clocking schemes.

(2) When you use the error detection cyclical redundancy check (CRC) feature, there is no degradation in F_{MAX}.

(3) The F_{MAX} specification is only achievable with Fitter options, MLAB Implementation In 16-Bit Deep Mode enabled.

Temperature Sensing Diode Specifications

Table 34 lists the internal TSD specification.

Table 34. Internal Temperature Sensing Diode Specification

Temperature Range	Accuracy	Offset Calibrated Option	Sampling Rate	Conversion Time	Resolution	Minimum Resolution with no Missing Codes
–40°C to 100°C	±8°C	No	1 MHz, 500 KHz	< 100 ms	8 bits	8 bits

Table 35 lists the specifications for the Stratix V external temperature sensing diode.

Description	Min	Тур	Max	Unit
I _{bias} , diode source current	8	—	200	μA
V _{bias,} voltage across diode	0.3	—	0.9	V
Series resistance		—	< 1	Ω
Diode ideality factor	1.006	1.008	1.010	

Duty Cycle Distortion (DCD) Specifications

Table 44 lists the worst-case DCD for Stratix V devices.

Table 44. Worst-Case DCD on Stratix V I/O Pins (1)

Symbol	C	1	C2, C2	L, 12, 12L		3, I3L, Syy	C4	4,14	Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	45	55	45	55	%

Note to Table 44:

(1) The DCD numbers do not cover the core clock network.

Configuration Specification

POR Delay Specification

Power-on reset (POR) delay is defined as the delay between the time when all the power supplies monitored by the POR circuitry reach the minimum recommended operating voltage to the time when the nSTATUS is released high and your device is ready to begin configuration.



For more information about the POR delay, refer to the *Hot Socketing and Power-On Reset in Stratix V Devices* chapter.

Table 45 lists the fast and standard POR delay specification.

Table 45. Fast and Standard POR Delay Specification (1)

POR Delay	Minimum	Maximum	
Fast	4 ms	12 ms	
Standard	100 ms	300 ms	

Note to Table 45:

(1) You can select the POR delay based on the MSEL settings as described in the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

JTAG Configuration Specifications

Table 46 lists the JTAG timing parameters and values for Stratix V devices.

Table 46. JTAG Timing Parameters and Values for Stratix V Devices

Symbol	Description	Min	Max	Unit
t _{JCP}	TCK clock period ⁽²⁾	30	—	ns
t _{JCP}	TCK clock period ⁽²⁾	167	—	ns
t _{JCH}	TCK clock high time ⁽²⁾	14	—	ns
t _{JCL}	TCK clock low time ⁽²⁾	14	—	ns
t _{JPSU (TDI)}	TDI JTAG port setup time	2	—	ns
t _{JPSU (TMS)}	TMS JTAG port setup time	3	—	ns

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×32	Disabled	Enabled	4
FFF X02	Enabled	Disabled	8
	Enabled	Enabled	8

Note to Table 49:

(1) Depending on the DCLK-to-DATA [] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA [] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Stratix V devices use the additional clock cycles to decrypt and decompress the configuration data.

Figure 11 shows the configuration interface connections between the Stratix V device and a MAX II or MAX V device for single device configuration.

Figure 11. Single Device FPP Configuration Using an External Host



Notes to Figure 11:

- (1) Connect the resistor to a supply that provides an acceptable input signal for the Stratix V device. V_{CCPGM} must be high enough to meet the V_{IH} specification of the I/O on the device and the external host. Altera recommends powering up all configuration system I/Os with V_{CCPGM} .
- (2) You can leave the nCEO pin unconnected or use it as a user I/O pin when it does not feed another device's nCE pin.
- (3) The MSEL pin settings vary for different data width, configuration voltage standards, and POR delay. To connect MSEL, refer to the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (4) If you use FPP ×8, use DATA [7..0]. If you use FPP ×16, use DATA [15..0].

IF the DCLK-to-DATA[] ratio is greater than 1, at the end of configuration, you can only stop the DCLK (DCLK-to-DATA[] ratio – 1) clock cycles after the last data is latched into the Stratix V device.

Table 50 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA[] ratio is 1.

Table 50. FPP Timing Parameters for Stratix V Devices (1)

Symbol	Parameter	Minimum	Maximum	Units
t _{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t _{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t _{CFG}	nCONFIG low pulse width	2	—	μS
t _{status}	nSTATUS low pulse width	268	1,506 ⁽²⁾	μS
t _{CF2ST1}	nCONFIG high to nSTATUS high	—	1,506 ⁽³⁾	μS
t _{CF2CK} (6)	nCONFIG high to first rising edge on DCLK	1,506	_	μS
t _{ST2CK} ⁽⁶⁾	nSTATUS high to first rising edge of DCLK	2	_	μS
t _{DSU}	DATA [] setup time before rising edge on DCLK	5.5	_	ns
t _{DH}	DATA [] hold time after rising edge on DCLK	0	_	ns
t _{CH}	DCLK high time	$0.45\times1/f_{MAX}$	—	S
t _{CL}	DCLK low time	$0.45\times1/f_{MAX}$	—	S
t _{CLK}	DCLK period	1/f _{MAX}	_	S
f	DCLK frequency (FPP ×8/×16)	—	125	MHz
f _{MAX}	DCLK frequency (FPP ×32)	—	100	MHz
t _{CD2UM}	CONF_DONE high to user mode ⁽⁴⁾	175	437	μS
+	CONTRACT high to an union analysis	4 × maximum		
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	DCLK period	—	
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	$\begin{array}{c} t_{\text{CD2CU}} + \\ (8576 \times \text{CLKUSR} \\ \text{period}) \ ^{(5)} \end{array}$	_	_

Notes to Table 50:

(1) Use these timing parameters when the decompression and design security features are disabled.

(2) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.

(3) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.

- (4) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.
- (5) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (6) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

FPP Configuration Timing when DCLK-to-DATA [] > 1

Figure 13 shows the timing waveform for FPP configuration when using a MAX II device, MAX V device, or microprocessor as an external host. This waveform shows timing when the DCLK-to-DATA [] ratio is more than 1.



Figure 13. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is >1 (1), (2)

Notes to Figure 13:

- (1) Use this timing waveform and parameters when the DCLK-to-DATA [] ratio is >1. To find out the DCLK-to-DATA [] ratio for your system, refer to Table 49 on page 55.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time as specified by the POR delay.
- (4) After power-up, before and during configuration, CONF_DONE is low.
- (5) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (6) "r" denotes the DCLK-to-DATA [] ratio. For the DCLK-to-DATA [] ratio based on the decompression and the design security feature enable settings, refer to Table 49 on page 55.
- (7) If needed, pause DCLK by holding it low. When DCLK restarts, the external host must provide data on the DATA [31..0] pins prior to sending the first DCLK rising edge.
- (8) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (9) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

Symbol	Parameter	Minimum	Maximum	Units
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	—
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t _{cd2cu} + (8576 × clkusr period)	_	—

Table 53. AS Timing Parameters for AS \times 1 and AS \times 4 Configurations in Stratix V Devices ^{(1), (2)} (Part 2 of 2)

Notes to Table 53:

(1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.

(2) t_{CF2CD}, t_{CF2ST0}, t_{CF2ST0}, t_{CF6}, t_{STATUS}, and t_{CF2ST1} timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63.

(3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

Passive Serial Configuration Timing

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

Figure 15. PS Configuration Timing Waveform ⁽¹⁾



Notes to Figure 15:

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds <code>nSTATUS</code> low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATAO is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

Remote System Upgrades

Table 56 lists the timing parameter specifications for the remote system upgrade circuitry.

Table 56. Remote System Upgrade Circuitry Timing Specifications	Table 56.	Remote System	Upgrade Circuitry	y Timing S	Specifications
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Parameter	Minimum	Maximum	Unit
t _{RU_nCONFIG} ⁽¹⁾	250	—	ns
t _{RU_nRSTIMER} ⁽²⁾	250	—	ns

Notes to Table 56:

- (1) This is equivalent to strobing the reconfiguration input of the ALTREMOTE_UPDATE megafunction high for the minimum timing specification. For more information, refer to the Remote System Upgrade State Machine section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (2) This is equivalent to strobing the reset_timer input of the ALTREMOTE_UPDATE megafunction high for the minimum timing specification. For more information, refer to the User Watchdog Timer section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

User Watchdog Internal Circuitry Timing Specification

Table 57 lists the operating range of the 12.5-MHz internal oscillator.

Table 57. 12.5-MHz Internal Oscillator Specifications

Minimum	Typical	Maximum	Units
5.3	7.9	12.5	MHz

I/O Timing

Altera offers two ways to determine I/O timing—the Excel-based I/O Timing and the Quartus II Timing Analyzer.

Excel-based I/O timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get an estimate of the timing budget as part of the link timing analysis. The Quartus II Timing Analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after you complete place-and-route.

 You can download the Excel-based I/O Timing spreadsheet from the Stratix V Devices Documentation web page.

Programmable IOE Delay

Table 58 lists the Stratix V IOE programmable delay settings.

Table 58. IOE Programmable Delay for Stratix V Devices (Part 1 of 2)

Parameter (1)	Available Settings	Min Offset (2)	Fast Model		Slow Model							
			Industrial	Commercial	C1	C2	C3	C4	12	13, 13YY	14	Unit
D1	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns
D2	32	0	0.230	0.244	0.415	0.415	0.459	0.503	0.417	0.456	0.500	ns